

SUBSTRATE PROCESSING APPARATUS, TEMPERATURE CONTROL DEVICE,
AND TEMPERATURE CONTROL METHOD

ABSTRACT

5 A plasma processing system has a supply unit 210, a
main body section 111, and a controller 2. The supply unit
210 is configured to be capable of supplying each of a
plurality of heat media each having a different
temperature. The main body section 111 has, formed
10 therein, a plurality of flow paths 1112 that respectively
allow the plurality of heat media to separately flow
therethrough, and is included in the plasma processing
system. The controller 2 is configured to perform control
so that in a case where a first heat medium of the
15 plurality of heat media is caused to flow through the flow
paths 1112 from the supply unit 210, a heat medium of the
plurality of heat media and other than the first heat
medium is discharged from the flow paths 1112.

20 Figure 3C